

TDK item description CGA4J2X8R1H683KT5***

Applications Automotive Grade

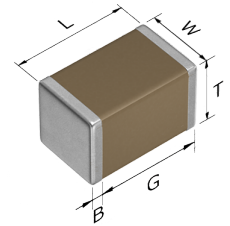
Feature AEC-Q200

High Temperature Application

Open Mode

Series CGA4(2012) [EIA 0805]

Status Production (Not Recommended for New Design)



Size

Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

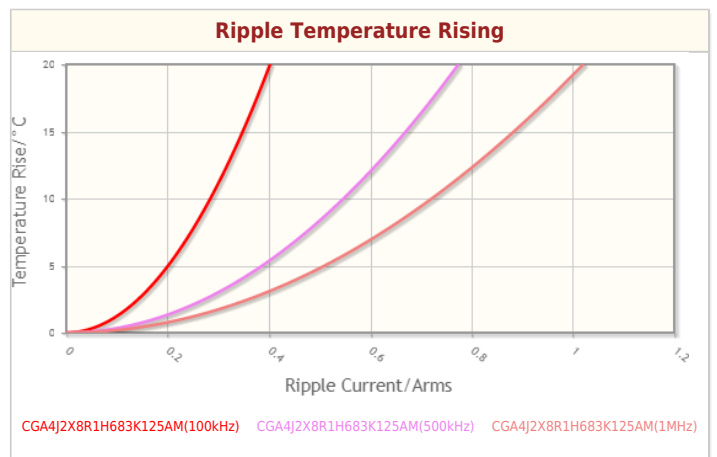
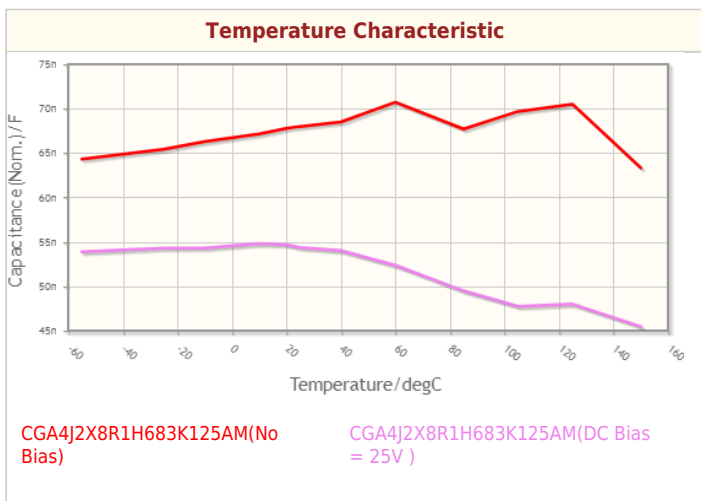
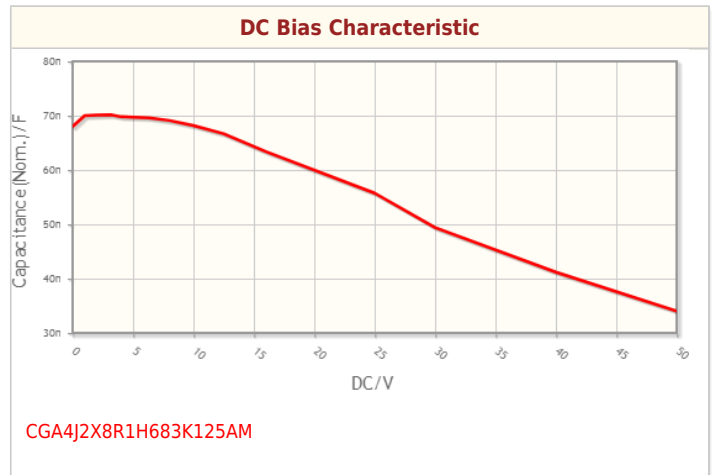
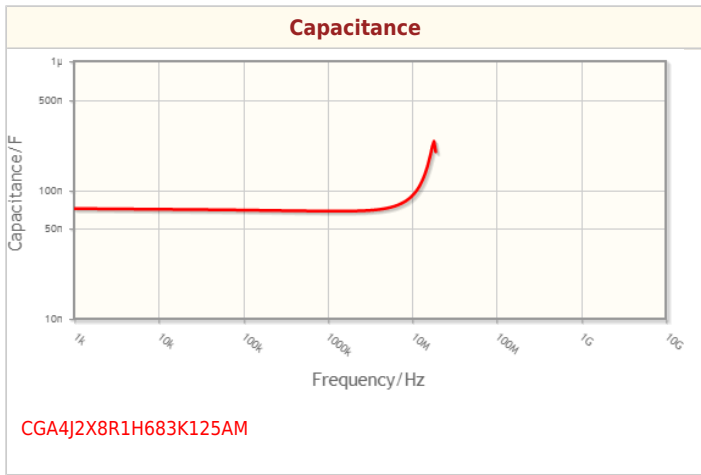
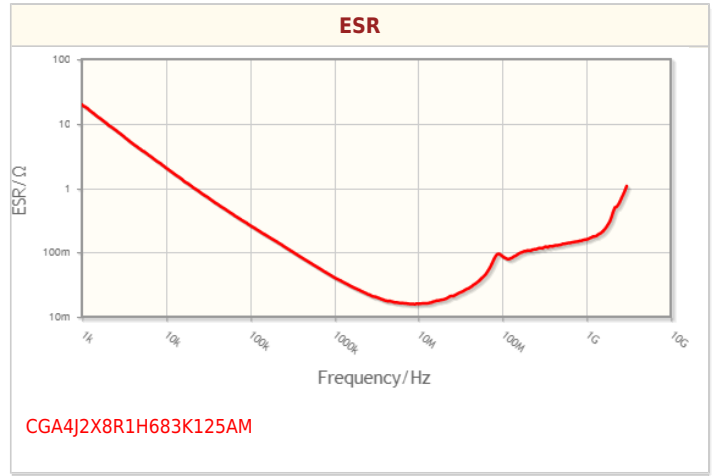
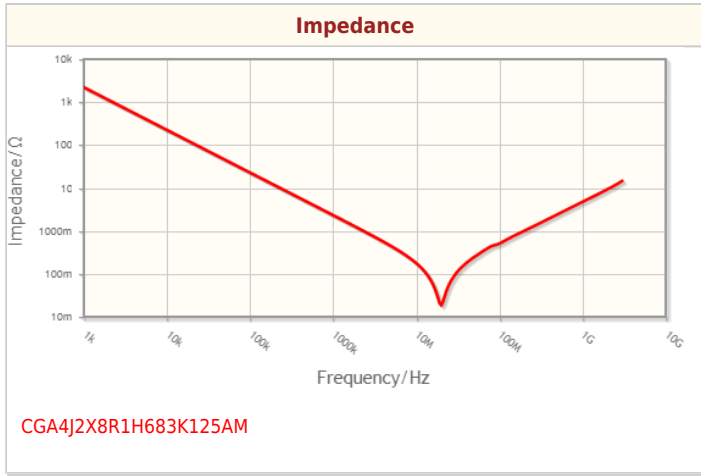
Electrical Characteristics

Capacitance	68nF ±10%
Rated Voltage	50VDC
Temperature Characteristic	X8R(±15%)
Dissipation Factor (Max.)	3%
Insulation Resistance (Min.)	7352MΩ

Other

Soldering Method	Wave (Flow)
	Reflow
AEC-Q200	YES
Packing	Embossed (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

Associated Images

